

MRF5175

2

The RF Line

NPN SILICON RF POWER TRANSISTOR

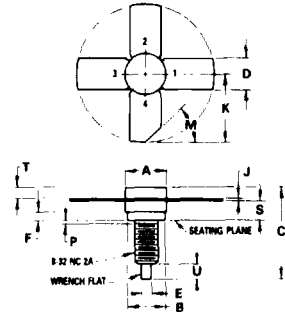
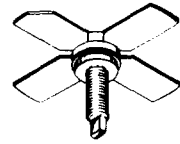
... designed primarily for wideband large-signal driver and predriver amplifier stages in the 200-600 MHz frequency range.

- Specified 28-Volt, 400-MHz Characteristics –
 Output Power = 5.0 Watts
 Minimum Gain = 11 dB
 Efficiency = 50%
- Characterized from 200 to 600 MHz
- Includes Series Equivalent Impedances

5 W – 400 MHz

**RF POWER
 TRANSISTOR**

NPN SILICON



STYLE 1
 PIN 1 EMITTER
 2 BASE
 3 EMITTER
 4 COLLECTOR

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	7.06	7.26	0.278	0.286
B	6.20	6.50	0.244	0.256
C	14.99	16.51	0.590	0.650
D	5.46	5.96	0.215	0.235
E	1.40	1.65	0.055	0.065
F	1.52	—	0.060	—
J	0.08	0.17	0.003	0.007
K	11.05	—	0.435	—
M	45° NOM	—	45° NOM	—
P	—	1.27	—	0.050
S	3.00	3.25	0.118	0.128
T	1.40	1.77	0.055	0.070
U	2.92	3.68	0.115	0.145

CASE 244-04

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V _{CEO}	33	V _{dc}
Collector-Base Voltage	V _{CBO}	60	V _{dc}
Emitter-Base Voltage	V _{EB0}	4.0	V _{dc}
Collector Current – Continuous	I _C	1.0	A _{dc}
Total Device Dissipation @ T _A = 25°C (1) Derate above 25°C	P _D	12 69	Watts mW/°C
Storage Temperature Range	T _{stg}	-85 to +200	°C

(1) This device is designed for RF operation. The total device dissipation rating applies only when the device is operated as an RF amplifier.

THERMAL CHARACTERISTICS

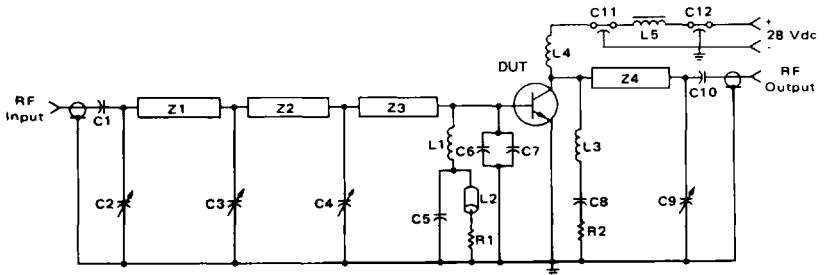
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	R _{θJC}	12	°C/W

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ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector-Emitter Breakdown Voltage ($I_C = 30\text{ mAdc}$, $I_B = 0$)	$V_{(BR)CEO}$	33	—	—	Vdc
Collector-Emitter Breakdown Voltage ($I_C = 30\text{ mAdc}$, $V_{BE} = 0$)	$V_{(BR)CES}$	60	—	—	Vdc
Emitter-Base Breakdown Voltage ($I_E = 1.0\text{ mAdc}$, $I_C = 0$)	$V_{(BR)EBO}$	4.0	—	—	Vdc
Collector Cutoff Current ($V_{CB} = 30\text{ Vdc}$, $I_E = 0$)	I_{CBO}	—	—	0.5	mAdc
ON CHARACTERISTICS					
DC Current Gain ($I_C = 250\text{ mAdc}$, $V_{CE} = 5.0\text{ Vdc}$)	h_{FE}	10	—	100	—
DYNAMIC CHARACTERISTICS					
Output Capacitance ($V_{CB} = 30\text{ Vdc}$, $I_E = 0$, $f = 1.0\text{ MHz}$)	C_{ob}	—	—	15	pF
FUNCTIONAL TESTS (Figure 1)					
Common-Emitter Amplifier Power Gain ($V_{CC} = 28\text{ Vdc}$, $P_{out} = 5.0\text{ W}$, $f = 400\text{ MHz}$)	G_{PE}	11	—	—	dB
Collector Efficiency ($V_{CC} = 28\text{ Vdc}$, $P_{out} = 5.0\text{ W}$, $f = 400\text{ MHz}$)	η	50	—	—	%

FIGURE 1 – 400 MHz TEST CIRCUIT SCHEMATIC



C1, C10	0.018 μF VITRAMON Chip	L4	6 Turns, #20 AWG, 1/8" ID
C2, C3, C9	1.0-10 pF JOHANSON Type 2951	L5	Ferrite Choke, FERROXCUBE VK200-20-4B
C4	1.0-20 pF JOHANSON Type 3906	R1	2.7 Ohm, 1/8 Watt, 10%
C5	100 pF UNDERWOOD (UNELCO)	R2	5.1 Ohm, 1/8 Watt, 10%
C6, C7	5.0 pF ATC Chip	Z1, Z3	Microstrip Line, 0.1" W x 0.5" L
C8	0.1 μF ERIE Disc Ceramic	Z2	Microstrip Line, 0.1" W x 0.4" L
C11, C12	680 pF ALLEN BRADLEY Feedthru	Z4	Microstrip Line, 0.075" W x 2.5" L
L1	3.9 μH Molded Choke	Board	Glass Teflon, $\epsilon_R = 2.56$, $t = 0.062$ "
L2	Ferrite Bead, FERROXCUBE 56-590-65-3B	Input/Output Connectors	Type N
L3	4 Turns, #22 AWG, 0.1" ID		

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FIGURE 2 – OUTPUT POWER versus FREQUENCY

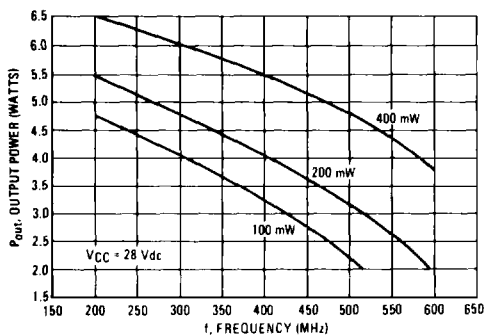


FIGURE 3 – OUTPUT POWER versus INPUT POWER

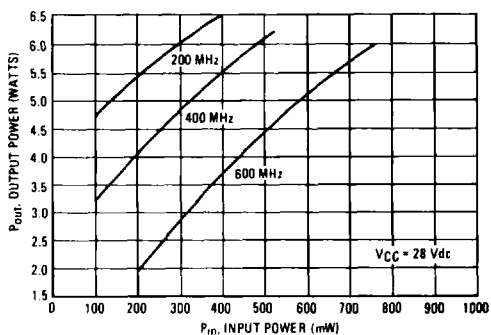


FIGURE 4 – OUTPUT POWER versus SUPPLY VOLTAGE

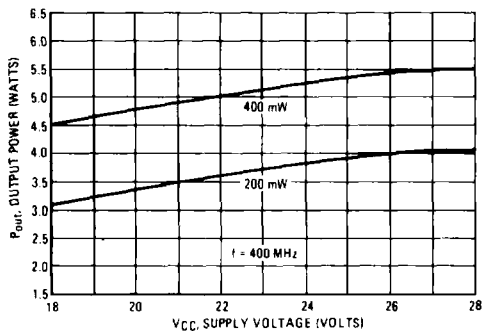
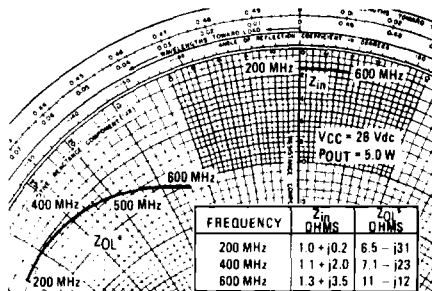


FIGURE 5 – SERIES EQUIVALENT IMPEDANCE



Z_{OL}^* = Conjugate of the optimum load impedance into which the device output operates at a given output power, voltage and frequency.

FIGURE 6 – 400 MHz TEST CIRCUIT

